

substrate in the example embodiment but significant benefit can be obtained if the expansions are not identical but at least substantially the same, e.g., within \pm 25% of one another or not differing by more than 2 ppm/ $^{\circ}$ C. More particularly, reasonable variations and modifications are possible in the component parts and/or arrangements of the subject combination arrangement within the scope of the foregoing disclosure, the drawings and the appended claims without departing from the spirit of the invention. In addition to variations and modifications in the component parts and/or arrangements, alternative uses will also be apparent to those skilled in the art.--

IN THE CLAIMS:

Please amend the claims as follows:

14. (Amended) An electronic assembly comprising:
a substrate having a first coefficient of thermal expansion;
a semiconductor chip having a second coefficient of thermal expansion
which is different than the first coefficient of thermal expansion;
a plurality of soldered joints connecting the semiconductor chip and
substrate;

wherein the chip and substrate across the respective soldered joints of the electronic assembly at room temperature have coefficient of thermal expansion difference induced elongation mismatches and stresses induced thereby in the electronic assembly from soldering; and

wherein the magnitude of the elongation mismatches and the stresses induced thereby in the electronic assembly are less than one-half that